

AMENDMENTS TO THE CLAIMS

Claims 1-13 (Canceled)

14. (New) A method for manufacturing a stamper for direct mastering, comprising the steps of:

forming a thermosensitive material layer capable of acting as a negative type by a laser beam on a substrate;

irradiating a laser beam to predetermined areas of said thermosensitive material layer so as to partially perform exposure; and

wet-etching said partially exposed thermosensitive material layer so as to form a fine pits-and-bumps pattern.

15. (New) A method for manufacturing a stamper for direct mastering according to claim 14, wherein said thermosensitive material layer contains an oxide of at least one element selected from the group consisting of molybdenum and tungsten.

16. (New) A method for manufacturing a stamper for direct mastering according to claim 14, wherein the step of forming said thermosensitive material layer comprises a reactive sputtering step which uses a target containing at least one element selected from the group consisting of molybdenum and tungsten.

17. (New) A method for manufacturing a stamper for direct mastering according to claim 16, wherein a partial pressure of argon gas is 0.1 to 0.20Pa, an oxygen partial pressure is 0.05 to 0.10Pa, and sputtering energy is 100 to 1000W in said reactive sputtering step.

18. (New) A method for manufacturing a stamper for direct mastering according to claim 14, further comprising the step of forming a heat-adjusting layer between said substrate and said thermosensitive material layer.

19. (New) A method for manufacturing a stamper for direct mastering according to claim 18, wherein a thermal conductivity of said heat-adjusting layer is one-tenth or lower than a thermal conductivity of said thermosensitive material layer.

20. (New) A method for manufacturing a stamper for direct mastering according to claim 18, wherein said heat-adjusting layer contains at least one resin selected from the group consisting of acryl-based resin, nylon-based resin, and polyester-based resin.

21. (New) A method for manufacturing a stamper for direct mastering according to claim 18, wherein said heat-adjusting layer contains at least one inorganic material selected from the group consisting of dielectric substances and metals, and said inorganic material has an absorption coefficient of 0.8 or higher with respect to a wavelength of said laser beam.

22. (New) A method for manufacturing a stamper for direct mastering according to claim 14, wherein said substrate is in the shape of disc-like stamper of which inner and outer diameters are processed.

23. (New) A method for manufacturing a stamper for direct mastering according to claim 14, further comprising the step of processing said substrate into the shape of stamper.

24. (New) A method for manufacturing a stamper for direct mastering according to claim 14, wherein the step of forming a fine pits-and-bumps pattern by said wet-etching comprises a step of etching said substrate so as to form the fine pits-and-bumps pattern using said partially exposed thermosensitive material layer as an etching mask.

25. (New) A stamper for direct mastering manufactured by means of a method of claim 14.

26. (New) An optical disc to be manufactured using the stamper of claim 25.